







Features

- · Glass passivated die construction
- Ideal for printed circuit boards

MMS50.06SIP

- High surge current capability
- High temperature soldering guarantee 265℃ /10 seconds, 0.375" (9.5mm) le length, 5lbs. (2.3kg) tension

Mechanical Data

Case: Molded plastic case Terminals: Plated leads solderable per MIL-STD-750, Method 2026 Polarity: Marked on Body Mounting Position: Any





Maximum Ratings and Thermal Characteristics (TA = 25°C unless otherwise noted)

| Symbol | Conditions | Values | Units |
|------------------|--|-------------|------------------|
| I(AV) | Maximum average forward output rectified current Tc =100 $^\circ\!\mathrm{C}$ | 50 | A |
| IFSM | Peak forward surge current single half sine-wave superimposed on rated load (JEDEC Method) | 500 | A |
| l ² t | Rating for fusing (t<10ms) | 1250 | A ² s |
| Visol | a.c.50HZ;r.m.s.;1min | 2500 | V |
| Rejc | Maximum thermal resistance per leg (1) | 1.5 | °C/W |
| TOR | Mounting Torque (Recommended torque:0.5 N.m) | 0.8 | N.m |
| Tj, TSTG | Operating Junction and storage temperature range | -55 to +150 | °C |
| Weight | Approximate Weight | 7 | g |

Electrical Characteristics (TA = 25°C unless otherwise noted)

| Symbol | Conditions | Values | Units |
|--------|--|------------|-------|
| VF | Maximum Instantaneous Forward Voltage per leg IFM =25A | 1.1 | V |
| IR | Maximum DC reverse current at rated $TA = 25^{\circ}C$ DC blocking voltage per leg $TA = 125^{\circ}C$ | 5.0 500 | μA |

Notes: (1) Junction to case with heatsink

(2) Recommended mounting position is to bolt down on heatsink with silicone thermal compound for maximum heat transfer with #6 screw





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